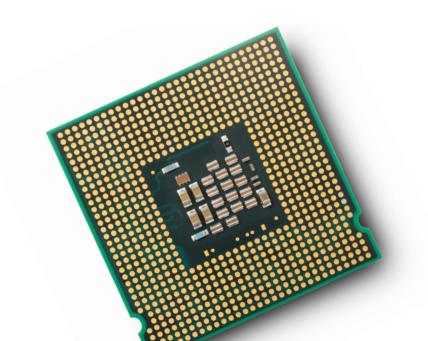




WHO WE ARE, WHAT WE DO.

We are scientists, engineers, thinkers, technologists, collaborators, and creators who understand critical details in materials technology.

Greene Tweed solutions deliver proven performance for leading semiconductor fabs, foundries, and OEMs.



Unparalleled Performance for Semiconductor Fabrication

Greene Tweed remains an innovator, keeping pace with the explosive advancements of the semiconductor industry. Chemraz® seals withstand the plasmas used in cutting-edge deposition and etch wafer processing. ONX® 600 composite components resist harsh chemicals used in semiconductor manufacturing. Our expert solutions include bonding, encapsulation, and coating capabilities for extra protection.

GREENE TWEED OVERVIEW

SOLUTIONS BY PROCESS AREA

Dielectric Etch

Conductor Etch

Ash/Strip

PECVD/PEALD

Wet Processing

SubFab

In addition to designing seals and composites that enable the manufacture of chips to power next-generation mobile devices, we also create:

Landing gear seals relied upon in 80%+ of commercial aircraft

Elastomeric seals which withstand 35,000+ pound per square inch (PSI) under 3 miles of ocean in deep water oil & gas wells

Composite wear parts that increase pump reliability to keep oil refineries running

Custom-designed structural components that reduce aircraft
weight to improve fuel efficiency

Electrical and fiber optic connectors which reliably transmit signals in the harshest environments

ADDITIONAL RESOURCES

Seal Handling Training

Chemical Compatibility Guide

1,900 employees across 11 countries support the most advanced global companies.



SOLUTIONS BY PROCESS AREA

Dielectric Etch

Conductor Etch

Ash/Strip

PECVD/PEALD

Wet Processing

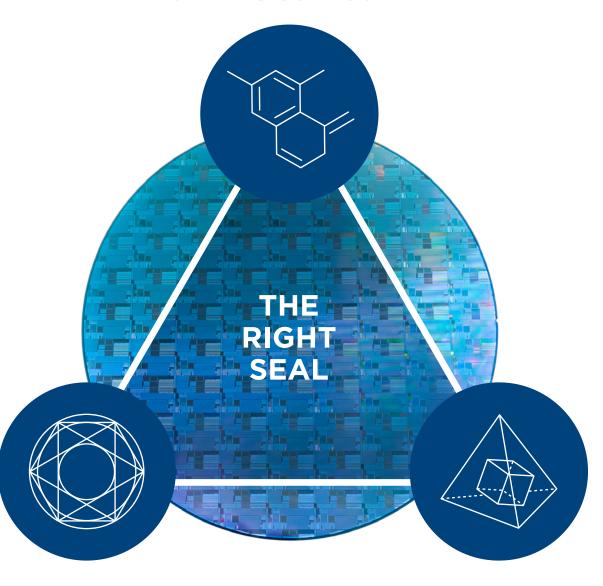
SubFab

ADDITIONAL RESOURCES

Seal Handling Training

Chemical Compatibility Guide

SEALING COMPOUND



HARDWARE GEOMETRY

the environment or niche the application, Greene Tweed offers customizable. high-performance sealing solutions in both industry

standard and non-standard

sizes and materials.

Greene Tweed sealing

chemicals and most

extreme temperatures.

solutions are built to resist the industry's harshest

No matter how demanding

WHO WE ARE, WHAT WE DO.

SEAL DESIGN



History of Semiconductor Customer Solutions:

Material and Design Innovations - Enabling Moore's Law

GREENE TWEED OVERVIEW

SOLUTIONS BY PROCESS AREA

Dielectric Etch

Conductor Etch

Ash/Strip

PECVD/PEALD

Wet Processing

SubFab





Seal Design

1987



The Beginning



Formed Seal Extended Life



Custom Seals Extended Life



Bonded Seal

- · Increased performance
- Extended life
- · Reduce particles

- · Increased performance
- Extended life
- Reduce sticking

Shielded Seal

- Reduce particles

Bonded Edge Exclusion Seal

· Increased performance

next >

- Extended life
- Reduce particles
- · Reduce sticking



Coated Seals

· Increased performance

PRESENT

- Extended life
- · Reduce particles
- · Reduce sticking

SUSTAINABILITY SMART

FUTURE

· Data delivery,

DATA

- Life expectancy in real time
- Recycling

ADDITIONAL RESOURCES

Seal Handling Training

Chemical Compatibility Guide

Semiconductor - Moore's Law

1965 **PRESENT**

Moore's Law - Decreasing Transistor Size

As Moore's Law has created extreme challenges in the Semiconductor Industry, GT has come along side our customers and developed innovative materials and designs that have met our customer's needs. We continue to do it today. Come and let Greene Tweed help you enable your processes.



GREENE TWEED OVERVIEW

SOLUTIONS BY PROCESS AREA

Dielectric Etch

Conductor Etch

Ash/Strip

PECVD/PEALD

Wet Processing

SubFab

ADDITIONAL RESOURCES

Seal Handling Training

Chemical Compatibility Guide

160 years material expertise & industry knowledge

On-going customer support

understanding
of the application
environment
and use

In-depth

TRUSTED PERFORMANCE

Customized engineered, quality solutions

Advanced, proprietary material technologies

Engineering expertise
& continuous partnership
through product
development

environments. We engineer for conditions where equipment failure is not an option. Our products are made for extreme temperatures, pressure, chemical corrosion, and mechanical wear.

Greene Tweed designs and

manufactures components, materials, and solutions

that perform in the harshest

WHY GREENE TWEED?



Oil & Gas

GREENE TWEED OVERVIEW

SOLUTIONS BY PROCESS AREA

Dielectric Etch

Conductor Etch

Ash/Strip

PECVD/PEALD

Wet Processing

SubFab

ADDITIONAL RESOURCES

Seal Handling Training

Chemical Compatibility Guide



Greene Tweed enables customers to operate efficiently and safely in the world's most demanding environments. We design, manufacture, and deliver innovative products with trusted performance for markets where failure is not an option.

MARKETS WE SERVE



Hydrogen

< back 6 next >



Greene

PRODUCTS

WE MANUFACTURE

Sealing Solutions

SOLUTIONS BY PROCESS AREA

Dielectric Etch

Conductor Etch

Ash/Strip

PECVD/PEALD

Wet Processing

SubFab



Chemraz®





Structural

Components

ADDITIONAL RESOURCES

Seal Handling Training



SOLUTIONS BY PROCESS AREA

Dielectric Etch

Conductor Etch

Ash/Strip

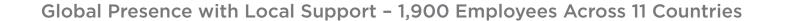
PECVD/PEALD

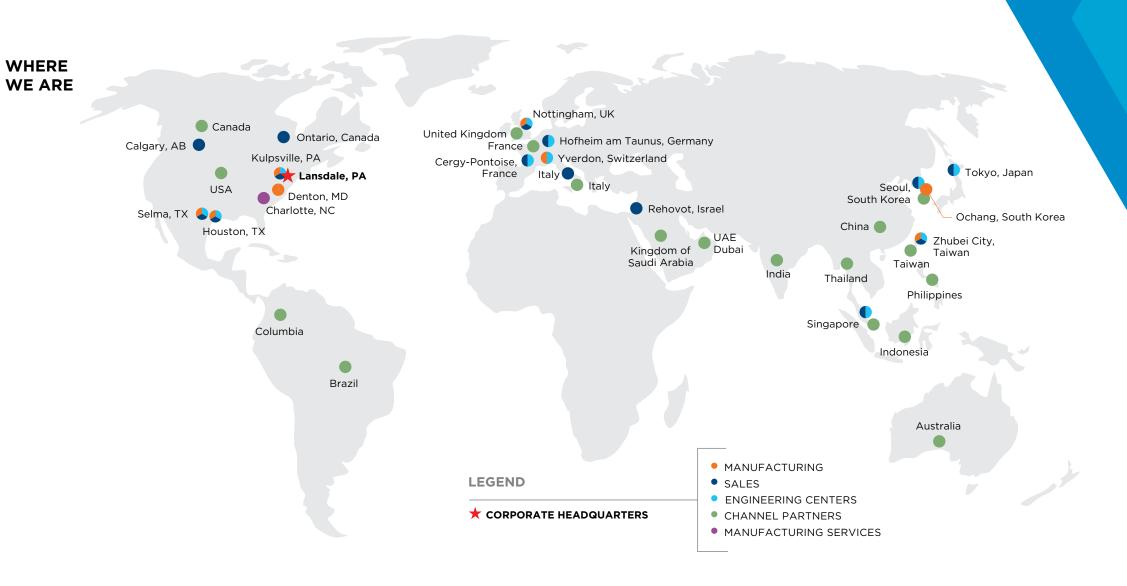
Wet Processing

SubFab

ADDITIONAL RESOURCES

Seal Handling Training







MANUFACTURING

Facilities

United Kingdom, United States, Switzerland, Taiwan, Korea

Certifications

ISO 9001:2015 ISO/IEC 17025:2017 ISO 14001:2015 AS9100:2016 EN9100:2018

Cleanrooms

Class 100 & 1000

Compression and injection molding capabilities

Materials Lab

Quality control of raw materials

Plasma Lab

Semiconductor parts testing using process gases

Accredited Testing Lab

ISO/IEC 17025:2017

Product Testing Lab

Pump wear rig, landing gear rig, sealing pressure vessel test rig, structural composites testing

Finite Elements Analysis (FEA)



Dielectric Etch

Conductor Etch

Ash/Strip

PECVD/PEALD

Wet Processing

SubFab

ADDITIONAL RESOURCES

Seal Handling Training





CHAMBER SOLUTIONS

When purity is a must, Greene Tweed offers a range of solutions for the dry etch vacuum environment.

Expert Innovation

Greene Tweed sealing solutions combat the harsh plasmas and chemicals in wafer fabrication processes, resisting wear and tear from cleaning, patterning, and deposition.



SOLUTIONS BY PROCESS AREA

Dielectric Etch

Conductor Etch

Ash/Strip

PECVD/PEALD

Wet Processing

SubFab

ADDITIONAL RESOURCES

Seal Handling Training



SOLUTIONS BY PROCESS AREA

Dielectric Etch

Conductor Etch

Ash/Strip

PECVD/PEALD

Wet Processing

SubFab

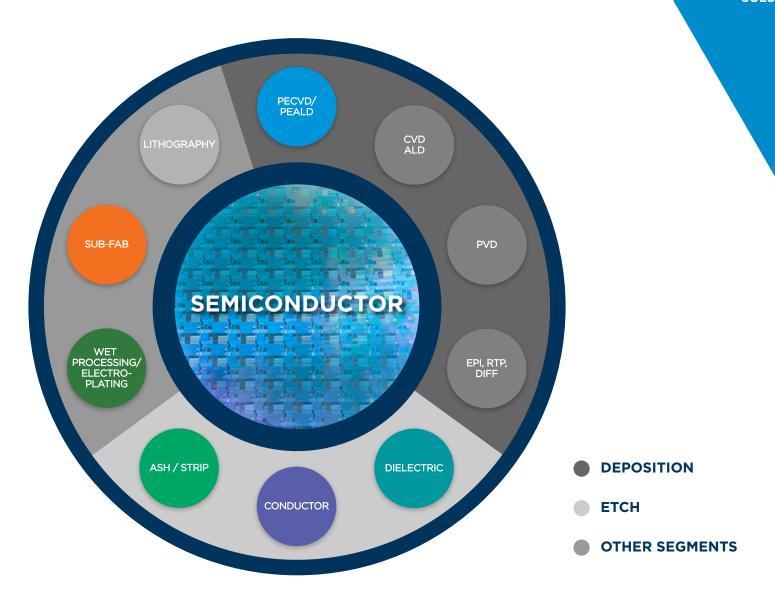
ADDITIONAL RESOURCES

Seal Handling Training

Chemical Compatibility Guide

SOLUTIONS BY PROCESS AREA

Explore the various solutions
Greene Tweed offers for each process area.



Click on the colored circles to jump to the solutions for those process areas.

The process areas indicated as gray circles will be activated in future versions of this guide.



GREENE TWEED OVERVIEW

SOLUTIONS BY PROCESS AREA

Dielectric Etch

Conductor Etch

Ash/Strip

PECVD/PEALD

Wet Processing

SubFab

ADDITIONAL RESOURCES

Seal Handling Training

Chemical Compatibility Guide

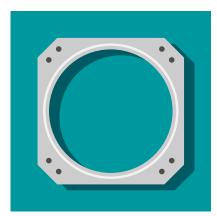
In dielectric etch tools, seals are typically used in chambers, gas entry/exhaust ports, chamber doors, and wafer chucks. Protection against oxygen-infused plasma is key in many etch chamber environments, which often break down non-resistant materials and cause harmful particulation, resulting in defective chips.

DIELECTRIC ETCH SOLUTIONS

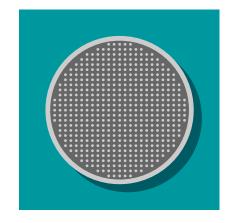
Our seals offer superior chemical resistance, minimal particle generation in plasma, and long service life to minimize maintenance and downtime.



Slit Valve Solutions



Chamber Seal Solutions



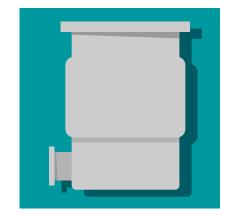
Electrostatic Chuck (ESC) Solutions



Pendulum Valve Solutions



End Effector Solutions



Turbomolecular Pump Solutions

Slit Valve Solutions

SOLUTIONS BY PROCESS AREA

GREENE TWEED OVERVIEW

Dielectric Etch

Conductor Etch

Ash/Strip

PECVD/PEALD

Wet Processing

SubFab

ADDITIONAL RESOURCES

Seal Handling **Training**

Chemical Compatibility Guide

The Shielded-Bonded Slit Valve Door (SBSV) and Bonded Slit Valve Door (BSV) significantly increase the life expectancy and performance of the door's seal during semiconductor plasma processing. Made from Greene Tweed's proprietary high-purity PTFE compound, Avalon® 56 HP, the SBSV shield enhances our unique BSV (Bonded Slit Valve) door design.

DIELECTRIC ETCH **SOLUTIONS**









End Effector Solutions



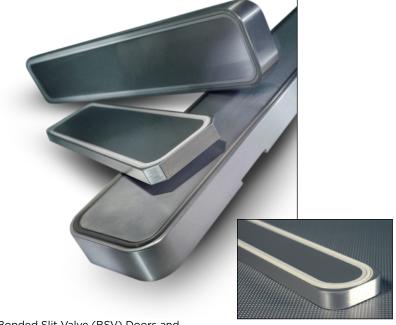
Chamber Seal Solutions



Pendulum Valve Solutions



Turbomolecular Pump Solutions



Bonded Slit Valve (BSV) Doors and Shielded-Bonded Slit Valve (SBSV) Door (inset) Click on the compound for more information.

Chemraz® G57 | Chemraz® XPE | Chemraz® 629

Click on the

explore other Chemraz® material

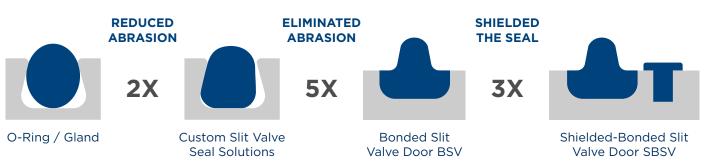
Elastomer Selection Wheel to

options

Chemraz® E38 | Chemraz® G38

ETCH (

SEAL DESIGN EVOLUTION



Contact a Greene Tweed sealing solutions engineer to learn how we can help solve your application concerns.

Slit Valve Solutions



Electrostatic Chuck Solutions



End Effector Solutions



Chamber Seal Solutions



Valve Solutions

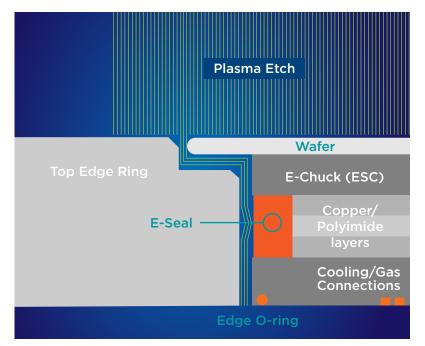
Pendulum



Turbomolecular Pump Solutions

Electrostatic Chuck (ESC) Solutions

E-seal refers to the electrostatic chuck seal application. Made from Greene Tweed's proprietary high-purity Chemraz® elastomers and Avalon® 56 HP PTFE fluoroplastics compounds, the e-seal significantly increases the life expectancy of the electrostatic chuck by protecting the outside diameter of the chuck from plasma erosion. To enable extreme cooling of the e-chuck, Greene Tweed provides custom MSE cryogenic seals that seal down to -150°C. Chemraz® 663 allows sealing down to -40°C.



E-Seal solution to protect the E-Chuck



Click on the compound for more information.

Chemraz® XPE | Chemraz® 663 | Avalon® 56 HP MSE® Cryogenic | Chemraz® 629

GREENE TWEED OVERVIEW

SOLUTIONS BY PROCESS AREA

Dielectric Etch

Conductor Etch

Ash/Strip

PECVD/PEALD

Wet Processing

SubFab

ADDITIONAL RESOURCES

Seal Handling Training

Chemical Compatibility Guide

Related Videos

SEAL DESIGN SOLUTIONS Small cross-sections, critical, high-precision



O-Ring (All Glands)



Elastomer (All Glands)



Plastic (All Glands)



Plastic Encapsulated O-ring (All Glands)



MSE (low temp) (All Glands)



Installation Fixtures

Click on the

Elastomer Selection

Wheel to

options

explore other Chemraz® material

> Contact a Greene Tweed sealing solutions engineer to learn how we can help solve your application concerns.

Wafer Transfer Robot End-Effector Solutions

SOLUTIONS BY PROCESS AREA

Greene Tweed offers end effector solutions (wafer handling/robot blade applications) including o-rings. Greene Tweed provides custom Chemraz® elastomer and Arlon® high-temperature thermoplastic solutions. A combination of material performance and engineering design optimizes wafer handling. This enhances slip resistance, wear resistance, and low sticking properties.

GREENE TWEED OVERVIEW

Conductor Etch

Dielectric Etch

Ash/Strip

PECVD/PEALD

Wet Processing

SubFab

DIELECTRIC ETCH SOLUTIONS





Electrostatic Chuck Solutions



End Effector Solutions



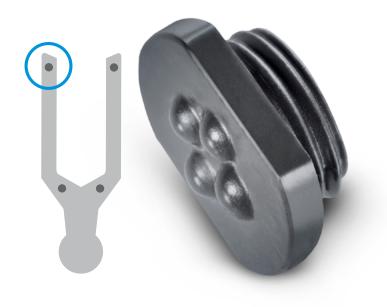
Chamber Seal Solutions



Pendulum Valve Solutions



Turbomolecular Pump Solutions



Arlon 3000XT® End-effector pad



Click on the compound for more information.

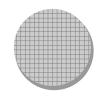
Chemraz® XCD | Arlon® | Arlon 3000XT®

ADDITIONAL RESOURCES

Seal Handling Training

Chemical Compatibility Guide

DESIGN SOLUTIONS



Custom Surface Finishes



Custom Surface Design



Extremely Small O-rings



Custom Bonded Designs



Custom Elastomer Pad Designs



Click on the

explore other Chemraz® material

Elastomer Selection Wheel to

options

Custom Plastic Pad Designs

Contact a Greene Tweed sealing solutions engineer to learn how we can help solve your application concerns.

Chamber Seal Solutions

GREENE TWEED OVERVIEW

SOLUTIONS BY PROCESS AREA

Dielectric Etch

Conductor Etch

Ash/Strip

PECVD/PEALD

Wet Processing

SubFab

ADDITIONAL RESOURCES

Seal Handling Training

Chemical Compatibility Guide

Chemraz® seals provide excellent performance in plasma etch process chambers. In particular they are compatible with fluorine and oxygen plasmas and are less susceptible to cracking. Seal design also needs to be considered to optimize seal performance.

DIELECTRIC ETCH SOLUTIONS







End Effector Solutions



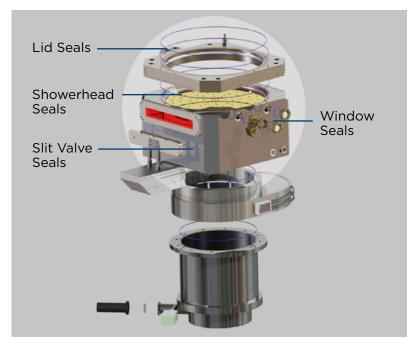
Chamber Seal Solutions



Pendulum Valve Solutions



Turbomolecular Pump Solutions



Typical process chamber.

PETCH CHAMBER PARTY ON THE PROPERTY OF THE PARTY OF THE P

Click on the compound for more information.

Chemraz® G57 | Chemraz® XPE | Chemraz® XCD

Chemraz® 629 | Chemraz® E38 | Chemraz® G38

SEAL DESIGN SOLUTIONS



O-Ring (All Glands)



Dovetail Seal (Dovetail Gland)



Glandlock® Seal (Half Dovetail Gland)



Formed Seal



Barrel Seal (All Glands)



Click on the

explore other

Elastomer Selection Wheel to

Chemraz®

material

options

Shielded Seal

Contact a Greene Tweed sealing solutions engineer to learn how we can help solve your application concerns.

Pendulum Valve Solutions

SOLUTIONS BY PROCESS AREA

GREENE TWEED OVERVIEW

Dielectric Etch

Conductor Etch

Ash/Strip

PECVD/PEALD

Wet Processing

SubFab

Click on the ETCH (Elastomer Selection Wheel to

explore other

Chemraz® material options

DIELECTRIC ETCH **SOLUTIONS**







End Effector Solutions



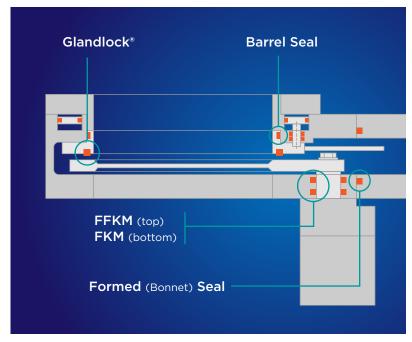
Chamber Seal Solutions



Pendulum Valve Solutions



Turbomolecular Pump Solutions



Seal placement in the pendulum valve.

Click on the compound for more information.

Chemraz® G57 | Chemraz® G38 | Chemraz® XCD

Chemraz® 629 | Chemraz® E38 | Enduro® LF10

ADDITIONAL RESOURCES

Seal Handling Training

Chemical Compatibility Guide

SEAL DESIGN SOLUTIONS



O-Ring (Dynamic Actuator)



Glandlock® Seal (Plate)



Our pendulum valve solutions significantly increase the life expectancy and performance

of the gate valves during semiconductor plasma processing. These solutions are designed

to eliminate premature failures caused by chemical and mechanical degradation.

Barrel Seal (Body)



Formed Seal (Bonnet)



Bonded Seal (Paddle)



Coated Seals (Dynamic Actuator)

Contact a Greene Tweed sealing solutions engineer to learn how we can help solve your application concerns.



Turbomolecular Pump Solutions

SOLUTIONS BY PROCESS AREA

GREENE TWEED OVERVIEW

Dielectric Etch

Conductor Etch

Ash/Strip

PECVD/PEALD

Wet Processing

SubFab

Click on the Elastomer Selection Wheel to explore other Chemraz® material options

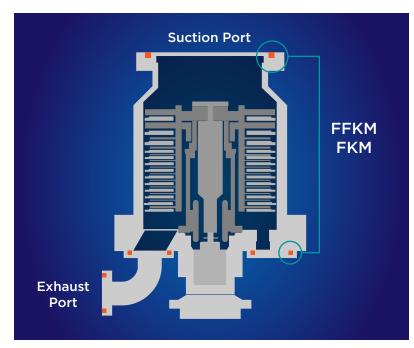
Click on the compound for more information.

ADDITIONAL RESOURCES

Seal Handling **Training**

Chemical Compatibility Guide

Chemraz® and Fusion® solutions can be used in turbomolecular pump applications up to 300°C and are compatible with deposition and etch process gases such as fluorine and oxygen. The combination elastomer material and seal design provides solutions that are less susceptible to cracking and overfill.



Seal locations on a turbomolecular pump

SEAL DESIGN SOLUTIONS



O-Ring (All Glands)



Custom Seal Design (Glandlock® Seal)



Custom Design Seal (Barrel Seal)



Chemraz® G57

ETCH (

Contact a Greene Tweed sealing solutions engineer to learn how we can help solve your application concerns.

DIELECTRIC ETCH SOLUTIONS





Electrostatic Chuck Solutions



End Effector Solutions



Chamber Seal Solutions

Valve Solutions



Turbomolecular Pump **Solutions**



GREENE TWEED OVERVIEW

SOLUTIONS BY PROCESS AREA

Dielectric Etch

Conductor Etch

Ash/Strip

PECVD/PEALD

Wet Processing

SubFab

ADDITIONAL RESOURCES

Seal Handling Training

Chemical Compatibility

Guide

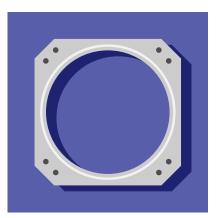
CONDUCTOR ETCH SOLUTIONS

Our seals offer superior chemical resistance, minimal particle generation in plasma, and long service life to minimize maintenance and downtime.

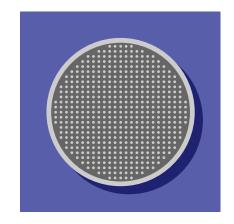


particulation, resulting in defective chips.

Slit Valve Solutions



Chamber Seal Solutions



In conductor etch tools, seals are typically used in chambers, gas entry/exhaust ports, chamber doors, and wafer chucks. Protection against oxygen and fluorine infused plasma is key in many

etch chamber environments, which often break down non-resistant materials and cause harmful

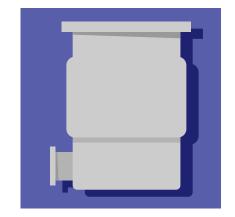
E-Seal Solutions



Pendulum Valve Solutions



End Effector Solutions



Turbomolecular Pump Solutions

Slit Valve Solutions

SOLUTIONS BY PROCESS AREA

GREENE TWEED OVERVIEW

Dielectric Etch

Conductor Etch

Ash/Strip

PECVD/PEALD

Wet Processing

SubFab

ADDITIONAL

RESOURCES

Seal Handling Training

Chemical Compatibility Guide

The Shielded-Bonded Slit Valve Door (SBSV) and Bonded Slit Valve Door (BSV) significantly increase the life expectancy and performance of the door's seal during semiconductor plasma processing. Made from Greene Tweed's proprietary high-purity PTFE compound, Avalon® 56 HP, the SBSV shield enhances our unique BSV (Bonded Slit Valve) door design.

CONDUCTOR ETCH SOLUTIONS







End Effector Solutions



Chamber Seal Solutions



Pendulum Valve Solutions



Turbomolecular Pump Solutions



Bonded Slit Valve (BSV) Doors and Shielded-Bonded Slit Valve (SBSV) Door (inset) Click on the compound for more information.

Chemraz® G57 | Chemraz® XPE | Chemraz® 629

Click on the

explore other Chemraz® material

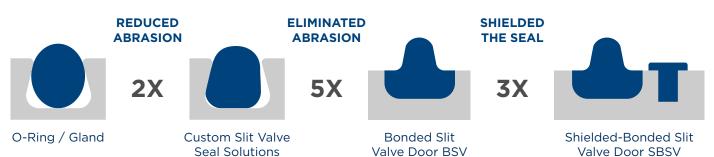
Elastomer Selection Wheel to

options

Chemraz® E38 | Chemraz® G38

ETCH (

SEAL DESIGN EVOLUTION



sealing solutions engineer to learn how we can help solve your application concerns.

Contact a Greene Tweed

Slit Valve Solutions



Electrostatic Chuck **Solutions**



End Effector Solutions



Chamber Seal Solutions

Valve Solutions

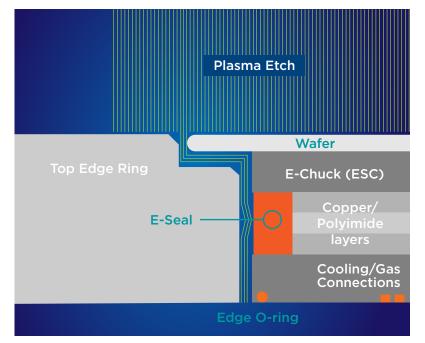




Turbomolecular Pump Solutions

Electrostatic Chuck (ESC) Solutions

E-seal refers to the electrostatic chuck seal application. Made from Greene Tweed's proprietary high-purity Chemraz® elastomers and Avalon® 56 HP PTFE fluoroplastics compounds, the e-seal significantly increases the life expectancy of the electrostatic chuck by protecting the outside diameter of the chuck from plasma erosion. To enable extreme cooling of the e-chuck, Greene Tweed provides custom MSE cryogenic seals that seal down to -150°C. Chemraz® 663 allows sealing down to -40°C.



E-Seal solution to protect the E-Chuck



Elastomer Selection Wheel to explore other Chemraz® material options

Click on the

ADDITIONAL RESOURCES

GREENE TWEED OVERVIEW

Dielectric Etch

Conductor Etch

PECVD/PEALD

Wet Processing

Ash/Strip

SubFab

SOLUTIONS BY PROCESS AREA

Seal Handling Training

Chemical Compatibility Guide

Related Videos

Click on the compound for more information.

Chemraz® XPE | Chemraz® 663 | Avalon® 56 HP MSE® Cryogenic | Chemraz® 629

SEAL DESIGN SOLUTIONS Small cross-sections, critical, high-precision



O-Ring (All Glands)



Elastomer (All Glands)



Plastic (All Glands)



Plastic Encapsulated O-ring (All Glands)



MSE (low temp) (All Glands)



Installation Fixtures

Contact a Greene Tweed sealing solutions engineer to learn how we can help solve your application concerns.



Wafer Transfer Robot End-Effector Solutions

SOLUTIONS BY PROCESS AREA

GREENE TWEED OVERVIEW

Dielectric Etch

Conductor Etch

Ash/Strip

PECVD/PEALD

Wet Processing

SubFab

Click on the Elastomer Selection Wheel to explore other Chemraz® material options

ADDITIONAL RESOURCES

Seal Handling Training

Chemical Compatibility Guide

Greene Tweed offers end effector solutions (wafer handling/robot blade applications) including o-rings. Greene Tweed provides custom Chemraz® elastomer and Arlon® high-temperature thermoplastic solutions. A combination of material performance and engineering design optimizes wafer handling. This enhances slip resistance, wear resistance, and low sticking properties.

CONDUCTOR ETCH SOLUTIONS







End Effector Solutions



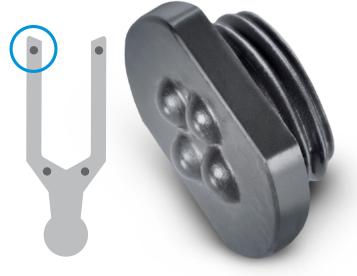
Chamber Seal Solutions



Pendulum Valve Solutions



Turbomolecular Pump Solutions



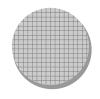
Arlon 3000XT® End-effector pad

ЕТСН

Click on the compound for more information.

Chemraz® XCD | Arlon® | Arlon 3000XT®

DESIGN SOLUTIONS



Custom Surface Finishes



Custom Surface Design



Extremely Small O-rings



Custom Bonded Designs



Custom Elastomer Pad Designs



Custom Plastic Pad Designs

Contact a Greene Tweed sealing solutions engineer to learn how we can help solve your application concerns.

Chamber Seal Solutions

GREENE TWEED OVERVIEW

SOLUTIONS BY PROCESS AREA

Dielectric Etch

Conductor Etch

Ash/Strip

PECVD/PEALD

Wet Processing

SubFab

SUBMIT

ADDITIONAL RESOURCES

Seal Handling Training

Chemical Compatibility Guide

Chemraz® seals provide excellent performance in plasma etch processes. In particular they are compatible with fluorine and oxygen plasmas and are less susceptible to cracking. Seal design also needs to be considered to optimize seal performance.



CONDUCTOR ETCH

SOLUTIONS





End Effector Solutions



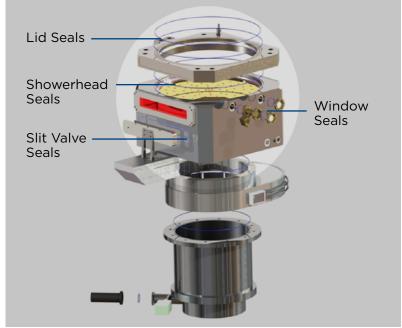
Chamber Seal Solutions



Pendulum Valve Solutions



Turbomolecular Pump Solutions



Typical process chamber.

Click on the compound for more information.

Chemraz® G57 | Chemraz® XPE | Chemraz® 629

Chemraz® E38 | Chemraz® G38

SEAL DESIGN SOLUTIONS



O-Ring (All Glands)



Dovetail Seal (Dovetail Gland)



Glandlock® Seal (Half Dovetail Gland)



Formed Seal



Barrel Seal (All Glands)



Click on the

explore other

Elastomer Selection Wheel to

Chemraz®

material

options

Shielded Seal

Contact a Greene Tweed sealing solutions engineer to learn how we can help solve your application concerns.



Pendulum Valve Solutions

Our pendulum valve solutions significantly increase the life expectancy and performance of the gate valves during semiconductor plasma processing. These solutions are designed to eliminate premature failures caused by chemical and mechanical degradation.

GREENE TWEED OVERVIEW

SOLUTIONS BY PROCESS AREA

Dielectric Etch

Conductor Etch

Ash/Strip

PECVD/PEALD

Wet Processing

SubFab

CONDUCTOR ETCH SOLUTIONS



Solutions



Electrostatic Chuck Solutions



End Effector Solutions



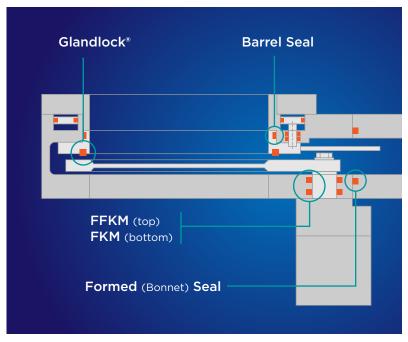
Chamber Seal Solutions



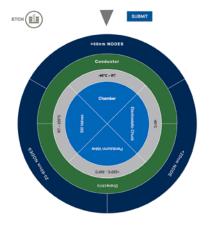
Pendulum Valve **Solutions**



Turbomolecular Pump Solutions



Seal placement in the pendulum valve.



Click on the Elastomer Selection Wheel to explore other Chemraz® material options

RESOURCES

Seal Handling Training

ADDITIONAL

Chemical Compatibility Guide

Click on the compound for more information.

Chemraz® G57 | Chemraz® G38 | Chemraz® 629

Chemraz® E38 | Enduro® LF10

SEAL DESIGN SOLUTIONS



O-Ring (Dynamic Actuator)



Glandlock® Seal (Plate)



Barrel Seal (Body)



Formed Seal (Bonnet)



Bonded Seal (Paddle)



Coated Seals (Dynamic Actuator)

Contact a Greene Tweed sealing solutions engineer to learn how we can help solve your application concerns.



Turbomolecular Pump Solutions

Chemraz® and Fusion® solutions can be used in turbomolecular pump applications up to 300°C and are compatible with deposition and etch process gases such as fluorine and oxygen.

The combination elastomer material and seal design provides solutions that are less susceptible

ETCH (

GREENE TWEED OVERVIEW

SOLUTIONS BY PROCESS AREA

Dielectric Etch

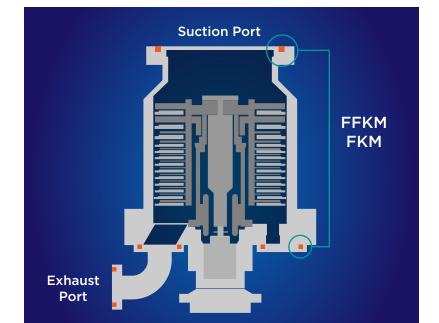
Conductor Etch

Ash/Strip

PECVD/PEALD

Wet Processing

SubFab



Seal locations on a turbomolecular pump

to cracking and overfill.

Flastomer Selection Wheel to explore other Chemraz® material options

Click on the

Click on the compound for more information.

Chemraz® G38

ADDITIONAL RESOURCES

Seal Handling Training

Chemical Compatibility Guide

CONDUCTOR ETCH SOLUTIONS



Electrostatic Chuck Solutions



End Effector Solutions



Chamber Seal Solutions



Pendulum Valve Solutions



Turbomolecular Pump Solutions

SEAL DESIGN SOLUTIONS



O-Ring (All Glands)



Custom Seal Design (Glandlock® Seal)



Custom Design Seal (Barrel Seal)





GREENE TWEED OVERVIEW

SOLUTIONS BY PROCESS AREA

PECVD/PEALD

Wet Processing

Dielectric Etch

Conductor Etch

Ash/Strip

SubFab

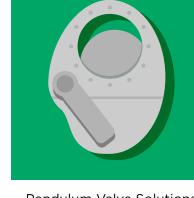
ASH/STRIP SOLUTIONS

Our seals offer superior chemical resistance, minimal particle generation in plasma, and long service life to minimize maintenance and downtime.



particulation, resulting in defective chips.

Slit Valve Solutions



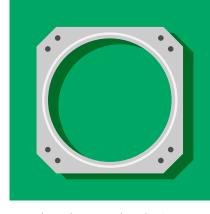
In ash/strip tools, seals are typically used in chambers, gas entry/exhaust ports, chamber doors, and wafer chucks. Protection against oxygen and hydrogen infused plasma is key in many ash/

strip chamber environments, which often break down non-resistant materials and cause harmful

Pendulum Valve Solutions



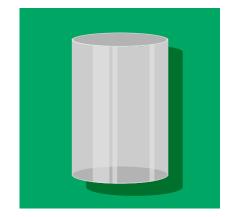
End Effector Solutions



Chamber Seal Solutions



Bell Jar Solutions



Plasma Tube Solutions

ADDITIONAL RESOURCES

Seal Handling Training

Slit Valve Solutions

SOLUTIONS BY PROCESS AREA

GREENE TWEED OVERVIEW

Dielectric Etch

Conductor Etch

Ash/Strip

PECVD/PEALD

Wet Processing

SubFab

Click on the Elastomer Selection Wheel to explore other Chemraz* material options

Click on the compound for more information.

Chemraz® 629

ADDITIONAL RESOURCES

Seal Handling Training

Chemical Compatibility Guide

The Shielded-Bonded Slit Valve Door (SBSV) and Bonded Slit Valve Door (BSV) significantly increase the life expectancy and performance of the door's seal during semiconductor plasma processing. Made from Greene Tweed's proprietary high-purity PTFE compound, Avalon® 56 HP, the SBSV shield enhances our unique BSV (Bonded Slit Valve) door design.

ASH/STRIP SOLUTIONS



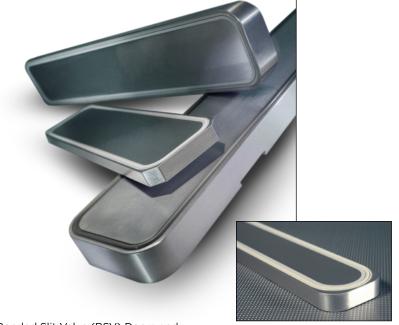












Bonded Slit Valve (BSV) Doors and Shielded-Bonded Slit Valve (SBSV) Door (inset)

SEAL DESIGN EVOLUTION



next >

Contact a Greene Tweed sealing solutions engineer to learn how we can help solve your application concerns.



ASH/STRIP SOLUTIONS

Slit Valve Solutions

Pendulum

Solutions

End Effector

Chamber Seal Solutions

Solutions

Bell Jar Solutions

Plasma Tube

Solutions

Pendulum Valve Solutions

GREENE TWEED OVERVIEW

SOLUTIONS BY PROCESS AREA

Dielectric Etch

Conductor Etch

Ash/Strip

PECVD/PEALD

Wet Processing

SubFab

Click on the Elastomer Selection Wheel to explore other Chemraz® material options

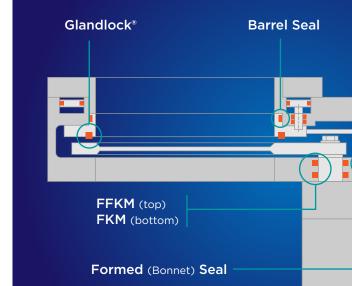
Click on the compound for more information.

ADDITIONAL RESOURCES

Seal Handling

Chemical Guide

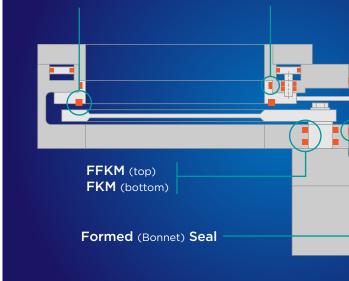
Our pendulum valve solutions significantly increase the life expectancy and performance of the gate valves during semiconductor plasma processing. These solutions are designed to eliminate premature failures caused by chemical and mechanical degradation.



Seal placement in the pendulum valve

Training

Compatibility



SEAL DESIGN SOLUTIONS



O-Ring (Dynamic Actuator)



Glandlock® Seal (Plate)



Barrel Seal (Body)



Formed Seal (Bonnet)



Chemraz® 629

Bonded Seal (Paddle)



Coated Seals (Dynamic Actuator)

Contact a Greene Tweed sealing solutions engineer to learn how we can help solve your application concerns.

Wafer Transfer Robot End-Effector Solutions

GREENE TWEED OVERVIEW

SOLUTIONS BY PROCESS AREA

Dielectric Etch

Conductor Etch

Ash/Strip

PECVD/PEALD

Wet Processing

SubFab

Click on the Elastomer Selection Wheel to explore other Chemraz® material options

Click on the compound for more information.

Chemraz® XCD | Arlon® | Arlon 3000XT®

ADDITIONAL RESOURCES

> Seal Handling Training

Chemical Compatibility Guide

Greene Tweed offers end effector solutions (wafer handling/robot blade applications) including o-rings. Greene Tweed provides custom Chemraz® elastomer and Arlon® high-temperature thermoplastic solutions. A combination of material performance and engineering design optimizes wafer handling. This enhances slip resistance, wear resistance, and low sticking properties.

ASH/STRIP SOLUTIONS









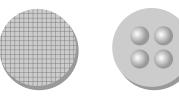






Arlon 3000XT® End-effector pad

DESIGN SOLUTIONS



Custom

Custom Surface Finishes Surface Design



Extremely Small O-rings



Custom Bonded Designs

next >



Custom Elastomer Pad Designs



Custom Plastic Pad Designs

Contact a Greene Tweed sealing solutions engineer to learn how we can help solve your application concerns.

Chamber Seal Solutions

GREENE TWEED OVERVIEW

SOLUTIONS BY PROCESS AREA

Dielectric Etch

Conductor Etch

Ash/Strip

PECVD/PEALD

Wet Processing

SubFab

Showerhead Seals

Slit Valve Seals

Window Seals

Typical process chamber.

SUMMT -68nm NOCS -62nm NOCS

Click on the

explore other

Elastomer Selection Wheel to

Chemraz®

material

options

Chemraz® XPE | Chemraz® G57 | Chemraz® 629

Chemraz® E38 | Chemraz® G38

Click on the compound for more information.

ADDITIONAL RESOURCES

Seal Handling Training

Chemical Compatibility Guide

ASH/STRIP SOLUTIONS









Chamber Seal Solutions



Bell Jar Solutions



Plasma Tube Solutions

SEAL DESIGN SOLUTIONS



O-Ring (All Glands)



Dovetail Seal (Dovetail Gland)



Chemraz® seals provide excellent performance in plasma etch processes. In particular they

are compatible with fluorene and oxygen plasmas and are less susceptible to cracking.

Seal design also needs to be considered to optimize seal performance.

Glandlock® Seal (Half Dovetail Gland)



Formed Seal



Barrel Seal (All Glands)



Shielded Seal (All Glands)

Bell Jar Solutions

SOLUTIONS BY PROCESS AREA

GREENE TWEED OVERVIEW

Dielectric Etch

Conductor Etch

Ash/Strip

PECVD/PEALD

Wet Processing

SubFab

ADDITIONAL RESOURCES

Seal Handling Training

Chemical Compatibility Guide

Our bell jar/quartz sealing solutions significantly increase performance including life expectancy and particulation in this application. Custom Chemraz® and seal design optimize performance of the bell jar during semiconductor plasma processing. These solutions are designed to eliminate premature failures caused by chemical and mechanical degradation and prevent quartz to metal contact.

ASH/STRIP SOLUTIONS









End Effector Solutions



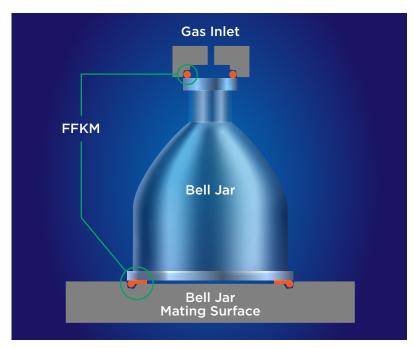
Chamber Seal Solutions



Bell Jar Solutions



Plasma Tube Solutions



Bell Jar application showing elastomer placement.

Click on the compound for more information.

Click on the

explore other Chemraz® material

Elastomer Selection Wheel to

options

Chemraz® 629

SEAL DESIGN SOLUTIONS



O-Ring



Design

Plasma Tube Solutions

GREENE TWEED OVERVIEW

SOLUTIONS BY PROCESS AREA

Dielectric Etch

Conductor Etch

Ash/Strip

PECVD/PEALD

Wet Processing

SubFab

ADDITIONAL RESOURCES

Seal Handling Training

Chemical Compatibility Guide

Our plasma tube solutions significantly increase life expectancy in this application. Custom Chemraz® and seal design optimize performance including high-temperature capability, reduced mechanical stress, and less sticking. Shielded designs also extend life expectancy in this application. Typical shield materials include Aluminum 6061-T6 and Avalon® 56 HP.

ASH/STRIP SOLUTIONS







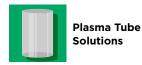
End Effector Solutions

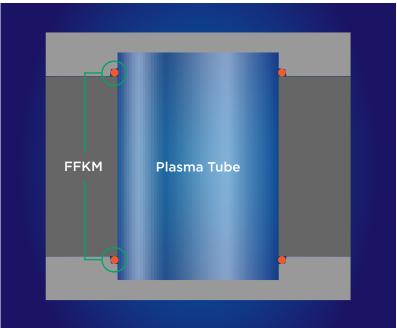


Chamber Seal Solutions



Bell Jar Solutions





Plasma tube with seal placement.

Elastomer Selection Wheel to explore other Chemraz* material options

Click on the

Click on the compound for more information.

Chemraz® XRZ

SEAL DESIGN SOLUTIONS



O-Ring



Custom Seal Designs



Shielded Seal Design



In CVD tools, seals are typically used in chambers, gas entry/exhaust ports, chamber doors, and wafer chucks. Protection against oxygen and fluorine infused plasma is key in many CVD chamber environments, which often break down non-resistant materials and cause harmful particulation, resulting in defective chips.

GREENE TWEED OVERVIEW

SOLUTIONS BY PROCESS AREA

Dielectric Etch

Conductor Etch

Ash/Strip

PECVD/PEALD

Wet Processing

SubFab

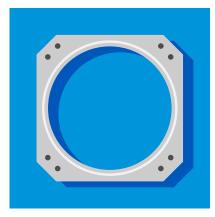
PECVD/PEALD SOLUTIONS

PLASMA ENHANCED
CHEMICAL VAPOR DEPOSITION
AND ATOMIC LAYER
DEPOSITION SOLUTIONS

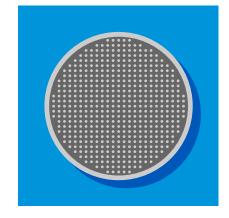
Our seals offer superior chemical resistance, minimal particle generation in plasma, and long service life to minimize maintenance and downtime.



Slit Valve Solutions



Chamber Seal Solutions



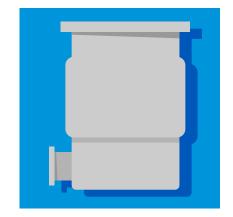
E-Seal Solutions



Pendulum Valve Solutions



End Effector Solutions



Turbomolecular Pump Solutions

ADDITIONAL RESOURCES

Seal Handling Training

SOLUTIONS BY PROCESS AREA

Dielectric Etch

Conductor Etch

Ash/Strip

PECVD/PEALD

Wet Processing

SubFab

SubF

ADDITIONAL RESOURCES

Seal Handling Training

Chemical Compatibility Guide

The Shielded-Bonded Slit Valve Door (SBSV) and Bonded Slit Valve Door (BSV) significantly increase the life expectancy and performance of the door's seal during semiconductor plasma processing. Made from Greene Tweed's proprietary high-purity PTFE compound, Avalon® 56 HP, the SBSV shield enhances our unique BSV (Bonded Slit Valve) door design.

PECVD/PEALD SOLUTIONS

PLASMA ENHANCED
CHEMICAL VAPOR DEPOSITION
AND ATOMIC LAYER
DEPOSITION SOLUTIONS



Slit Valve Solutions



Electrostatic Chuck Solutions



End Effector Solutions



Chamber Seal Solutions



Pendulum Valve Solutions



Turbomolecular Pump Solutions



Bonded Slit Valve (BSV) Doors and Shielded-Bonded Slit Valve (SBSV) Door (inset)

Click on the compound for more information.

SUBMIT

Chemraz® XRZ | Chemraz® G20 | Chemraz® 629

Click on the

Elastomer Selection

Wheel to

Chemraz® material

options

explore other

Chemraz® G13

SEAL DESIGN EVOLUTION



next >

Contact a Greene Tweed sealing solutions engineer to learn how we can help solve your application concerns.

SOLUTIONS BY PROCESS AREA

Dielectric Etch

Conductor Etch

Ash/Strip

PECVD/PEALD

Wet Processing

SubFab

Wheel to explore other Chemraz® material options

Click on the

Elastomer Selection

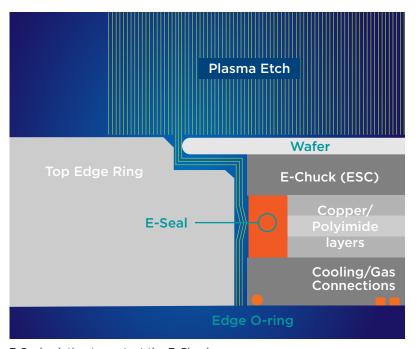
ADDITIONAL RESOURCES

Seal Handling Training

Chemical Compatibility Guide

Related Videos

E-seal refers to the electrostatic chuck seal application. Made from Greene Tweed's proprietary high-purity Chemraz® elastomers and Avalon® 56 HP PTFE fluoroplastics compounds, the e-seal significantly increases the life expectancy of the electrostatic chuck by protecting the outside diameter of the chuck from plasma erosion. To enable extreme cooling of the e-chuck, Greene Tweed provides custom MSE cryogenic seals that seal down to -150°C. Chemraz® 663 allows sealing down to -40°C.



E-Seal solution to protect the E-Chuck

Click on the compound for more information.

Chemraz® XPE | Chemraz® 663 | Chemraz® 629

Avalon® 56 HP | MSE® Cryogenic

End Effector Solutions

PECVD/PEALD SOLUTIONS

CHEMICAL VAPOR DEPOSITION

PLASMA ENHANCED

AND ATOMIC LAYER

DEPOSITION SOLUTIONS

Slit Valve Solutions

Electrostatic

Chuck

Solutions



Chamber Seal Solutions

Valve Solutions





Turbomolecular Pump Solutions

SEAL DESIGN SOLUTIONS Small cross-sections, critical, high-precision



O-Ring (All Glands)



Elastomer (All Glands)



Plastic (All Glands)



Plastic Encapsulated O-ring (All Glands)



MSE (low temp) (All Glands)



Installation Fixtures

Contact a Greene Tweed sealing solutions engineer to learn how we can help solve your application concerns.



Wafer Transfer Robot End-Effector Solutions

GREENE TWEED OVERVIEW

SOLUTIONS BY PROCESS AREA

Dielectric Etch

Conductor Etch

Ash/Strip

PECVD/PEALD

Wet Processing

SubFab

ADDITIONAL RESOURCES

Seal Handling Training

Chemical Compatibility Guide

Greene Tweed offers end effector solutions (wafer handling/robot blade applications) including o-rings. Greene Tweed provides custom Chemraz® elastomer and Arlon® high-temperature thermoplastic solutions. A combination of material performance and engineering design optimizes wafer handling. This enhances slip resistance, wear resistance, and low sticking properties.

PECVD/PEALD SOLUTIONS

PLASMA ENHANCED
CHEMICAL VAPOR DEPOSITION
AND ATOMIC LAYER
DEPOSITION SOLUTIONS



Slit Valve Solutions



Electrostatic Chuck Solutions



End Effector Solutions



Chamber Seal Solutions



Pendulum Valve Solutions



Turbomolecular Pump Solutions



Arlon 3000XT® End-effector pad

PERMINDES CYD and ALD APC - AT Chamber DODGE - D. ST. O. ANY - D. ST. O'NE - D. ST. O'NE

Click on the compound for more information.

SUBMIT

Chemraz® XCD | Arlon® | Arlon 3000XT®

DESIGN SOLUTIONS



Custom Surface Finishes



Custom Surface Design



Extremely Small O-rings



Custom Bonded Designs



Custom Elastomer Pad Designs



Click on the

explore other

Elastomer Selection

Wheel to

Chemraz® material

options

Custom Plastic Pad Designs

Contact a Greene Tweed sealing solutions engineer to learn how we can help solve your application concerns.



Chamber Seal Solutions

GREENE TWEED OVERVIEW

SOLUTIONS BY PROCESS AREA

Dielectric Etch

Conductor Etch

Ash/Strip

PECVD/PEALD

Wet Processing

SUBMIT

Selection Wheel to explore other Chemraz®

Click on the

Elastomer

material

options

SubFab

ADDITIONAL RESOURCES

Seal Handling Training

Chemical Compatibility Guide

Lid Seals Showerhead Seals Window Seals Slit Valve Seals

Typical process chamber.

Click on the compound for more information.

Chemraz® XRZ | Chemraz® G20 | Chemraz® 629

Chemraz® G13 | Enduro® LF10

Chamber Seal Solutions

PECVD/PEALD SOLUTIONS

CHEMICAL VAPOR DEPOSITION

PLASMA ENHANCED

AND ATOMIC LAYER

DEPOSITION SOLUTIONS

Slit Valve

Solutions

Electrostatic

End Effector

Solutions

Chuck Solutions



Pendulum Valve Solutions



Turbomolecular Pump Solutions

SEAL DESIGN SOLUTIONS



O-Ring (All Glands)



Dovetail Seal (Dovetail Gland)



Chemraz® seals provide excellent performance in plasma etch processes. In particular they

are compatible with fluorene and oxygen plasmas and are less susceptible to cracking.

Seal design also needs to be considered to optimize seal performance.

Glandlock® Seal (Half Dovetail Gland)



Formed Seal



Barrel Seal (All Glands)



Shielded Seal (All Glands)



Pendulum Valve Solutions

GREENE TWEED OVERVIEW

SOLUTIONS BY PROCESS AREA

Dielectric Etch

Conductor Etch

Ash/Strip

PECVD/PEALD

Wet Processing

SubFab

Click on the Elastomer Selection Wheel to explore other Chemraz* material options

Seal Handling Training

ADDITIONAL

RESOURCES

Chemical Compatibility Guide

Our pendulum valve solutions significantly increase the life expectancy and performance of the gate valves during semiconductor plasma processing. These solutions are designed to eliminate premature failures caused by chemical and mechanical degradation.

PECVD/PEALD SOLUTIONS PLASMA ENHANCED CHEMICAL VAPOR DEPOSITION

AND ATOMIC LAYER
DEPOSITION SOLUTIONS



Slit Valve Solutions



Electrostatic Chuck Solutions



End Effector Solutions

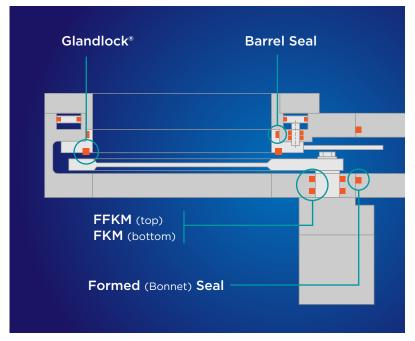


Chamber Seal Solutions

Pendulum Valve Solutions







Seal placement in the pendulum valve

Click on the compound for more information.

Chemraz® XRZ | Chemraz® G20 | Chemraz® 629

Chemraz® G13 | Enduro® LF10

SEAL DESIGN SOLUTIONS



O-Ring (Dynamic Actuator)



Glandlock® Seal (Plate)



Barrel Seal (Body)



Formed Seal (Bonnet)



Bonded Seal (Paddle)



Coated Seals (Dynamic Actuator)

Contact a Greene Tweed sealing solutions engineer to learn how we can help solve your application concerns.



Turbomolecular Pump Solutions

SOLUTIONS BY PROCESS AREA

GREENE TWEED OVERVIEW

Dielectric Etch

Conductor Etch

Ash/Strip

PECVD/PEALD

Wet Processing

SubFab

Click on the

Elastomer Selection

Wheel to

Chemraz® material

options

explore other

ADDITIONAL RESOURCES

Seal Handling Training

Chemical Compatibility Guide

Chemraz[®] and Fusion[®] solutions can be used in turbomolecular pump applications up to 300°C and are compatible with deposition and etch process gases such as fluorine and oxygen. The combination elastomer material and seal design provides solutions that are less susceptible to cracking and overfill.

PECVD/PEALD SOLUTIONS CHEMICAL VAPOR DEPOSITION **DEPOSITION SOLUTIONS**



Electrostatic Chuck Solutions

Slit Valve Solutions

PLASMA ENHANCED

AND ATOMIC LAYER



End Effector Solutions



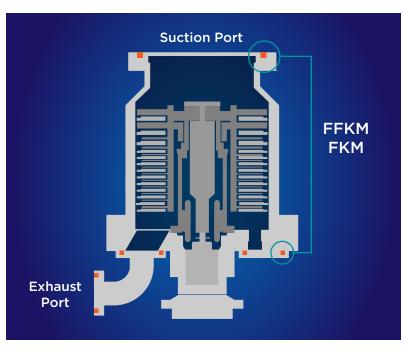
Chamber Seal Solutions



Pendulum Valve Solutions



Turbomolecular Pump **Solutions**



Seal locations on a turbomolecular pump

SEAL DESIGN SOLUTIONS



O-Ring (All Glands)



Custom Seal Design (Glandlock® Seal)



Custom Design Seal (Barrel Seal)



Chemraz® G20

Click on the compound for more information.



GREENE TWEED OVERVIEW

SOLUTIONS BY PROCESS AREA

Dielectric Etch

Conductor Etch

Ash/Strip

PECVD/PEALD

Wet Processing

SubFab

ADDITIONAL RESOURCES

Seal Handling Training

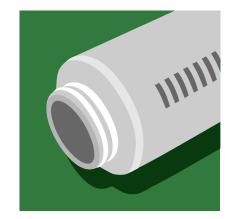
Chemical Compatibility Guide

In wet wafer processing tools, seals are typically used in wet chambers, electroplating, filter cartridges, and chillers. Sealing against a wide variety of chemistries including, acids, DI water, and electroplating solutions. High material compatibility and purity ensures cleanliness in the systems.

WET PROCESSING SOLUTIONS

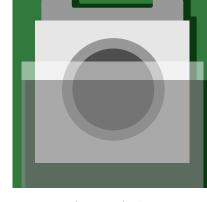
DI WATER **WET ETCH** WAFER CLEANS

Our seals offer superior chemical resistance, minimal particle generation in plasma, and long service life to minimize maintenance and downtime.



Filter Cartridge Seals

Wet Chamber Seal Solutions



Electroplating

Engineered Components



Chillers





WET PROCESSING SOLUTIONS

DI WATER WET ETCH WAFER CLEANS



Filter Cartridge Seals



Electroplating Seal Solutions



Engineered Component Solutions



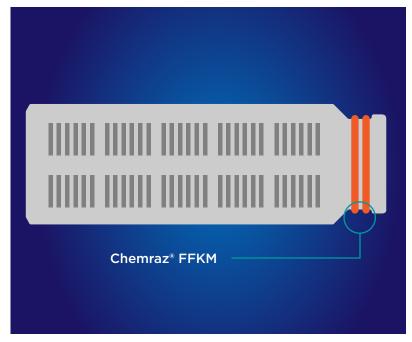
Wet Chamber Seal Solutions



Chillers

Filter Cartridge Seal Solutions

Chemraz® seals provide excellent performance in wet chemistries. In particular they are compatible with water, wet etch, and wafer clean chemistries and can handle these processes at high temperatures of 200°C or more. Chemraz® seals show low TOCs (Total Oxidizable Carbon), low leachable trace metals, and low ionic contamination in wet processing environments. Chemraz® materials have excellent resistance in these applications.



Seal placement on a filter cartridge

Click on the Elastomer Selection Wheel to explore other Chemraz* material options

ADDITIONAL RESOURCES

GREENE TWEED OVERVIEW

Dielectric Etch

Conductor Etch

PECVD/PEALD

Wet Processing

Ash/Strip

SubFab

SOLUTIONS BY PROCESS AREA

Seal Handling Training

Chemical Compatibility Guide

Chemraz® 551 | Chemraz® 570

UltraClean Chemraz® post cleaning process

Click on the compound for more information.

SEAL DESIGN SOLUTIONS



O-Ring (All Glands)



Custom Seals (All Gland)



Plastic Encapsulated O-ring (All Glands) Contact a Greene Tweed sealing solutions engineer to learn how we can help solve your application concerns.



Electroplating Seal Solutions

Chemraz® seals provide excellent performance in electroplating chemistries. These include, WLP-wafer level packaging, TSV-thru silicon via, and BEOL-back end of line-interconnect applications and processes at temperature of 200°C or more. Enduro® coatings extend seal life by allowing effective part cleaning and resisting plate-up on seal surfaces.

WET PROCESSING SOLUTIONS

DI WATER WET ETCH WAFER CLEANS



Filter Cartridge Seals



Electroplating Seal Solutions



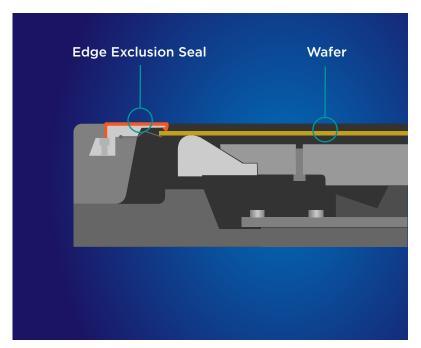
Engineered Component Solutions



Wet Chamber Seal Solutions



Chillers



Typical process chamber.

SUBMIT >60nm NODES Acids 30-220°C Enctrophring The Day Street Control of the Control of the

Click on the Elastomer Selection Wheel to explore other Chemraz* material options

ADDITIONAL RESOURCES

GREENE TWEED OVERVIEW

Dielectric Etch

Conductor Etch

PECVD/PEALD

Wet Processing

Ash/Strip

SubFab

SOLUTIONS BY PROCESS AREA

Seal Handling Training

Chemical Compatibility Guide

Click on the compound for more information.

Chemraz® 570 | Enduro® LF10

UltraClean Chemraz® post cleaning process

SEAL DESIGN SOLUTIONS



O-Ring (All Glands)



Custom Seals
(All Gland)





Contact a Greene Tweed sealing solutions engineer to learn how we can help solve your application concerns.



WET PROCESSING **SOLUTIONS**

DI WATER WET ETCH WAFER CLEANS



Filter Cartridge Seals



Electroplating Seal Solutions



Engineered Component Solutions



Wet Chamber Seal Solutions



Chillers

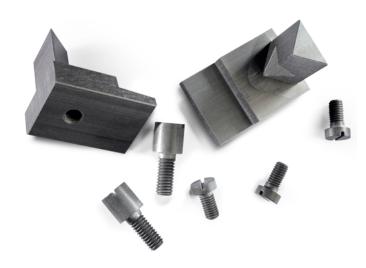
Engineered Component Solutions

Engineered component solutions include custom designed and make to print chamber components like wafer holders, pins or screws. Materials highlighted are: Avalon® 56 HP & ONX® 600.

Avalon® fluoroplastic grades provide excellent purity and chemical compatibility. Precision components made from Avalon® 56 HP versus standard PTFE can increase component service life.

ONX® 600 fluoroplastic composites can be useful in a range of applications offering benefits such as excellent mechanical strength, ESD protection in aggressive conditions, high purity and chemical resistance. Large diameter disks are available for ONX® 600 (capability up to 508mm) as well as turnkey manufactured components.

In addition to providing low ion contamination and low metal extractables, these engineered thermoplastic and composite solutions enhance overall tool performance.



ONX® 600 wafer chucks and screws

DESIGN SOLUTIONS



Wafer Holder Chuck



Chamber Component



Click on the Elastomer Selection Wheel to explore other Chemraz® material options

Click on the compound for more information.

Avalon® 56 HP | ONX® 600

GREENE TWEED OVERVIEW

SOLUTIONS BY PROCESS AREA

Dielectric Etch

Conductor Etch

Ash/Strip

PECVD/PEALD

Wet Processing

SubFab

ADDITIONAL RESOURCES

Seal Handling Training

Chemical Compatibility Guide



WET PROCESSING SOLUTIONS

DI WATER WET ETCH WAFER CLEANS



Filter Cartridge Seals



Electroplating Seal Solutions



Engineered Component Solutions



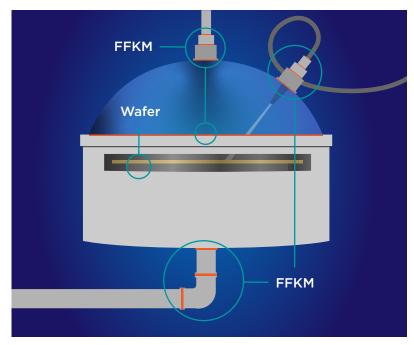
Wet Chamber Seal Solutions



Chillers

Wet Chamber Seal Solutions

Chemraz® seals provide excellent performance in wet chemistries. In particular they are compatible with water, wet etch, and wafer clean chemistries and can handle these processes at high temperatures of 200°C or more. Chemraz seals show low TOCs, low leachable trace metals, and low ionic contamination in wet processing environments. Chemraz materials have excellent resistance in these applications.



Wet etch, wet clean chambers.

SUBMIT > 69 m NODES Acids 30 - 220°C Enetropheiny Page 10 - 200°C 10 -

Click on the Elastomer Selection Wheel to explore other Chemraz* material options

> ADDITIONAL RESOURCES

GREENE TWEED OVERVIEW

Dielectric Etch

Conductor Etch

PECVD/PEALD

Wet Processing

Ash/Strip

SubFab

SOLUTIONS BY PROCESS AREA

Seal Handling Training

Chemical Compatibility Guide

Click on the compound for more information.

Chemraz® 551 | Chemraz® 570

UltraClean Chemraz® post cleaning process

SEAL DESIGN SOLUTIONS



O-Ring (All Glands)



Custom Seals (All Gland)



Plastic Encapsulated O-ring (All Glands) Contact a Greene Tweed sealing solutions engineer to learn how we can help solve your application concerns.



WET PROCESSING

DI WATER WET ETCH WAFER CLEANS

SOLUTIONS



Filter Cartridge Seals



Electroplating Seal Solutions



Engineered Component Solutions



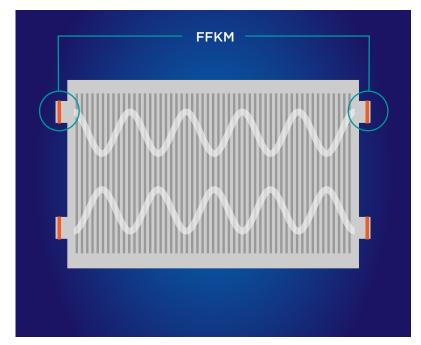
Wet Chamber Seal Solutions



Chillers

Chiller Seal Solutions

Chemraz® seals provide excellent performance in heat exchange systems including chillers. In particular they are compatible with water, heat exchange fluids, and coolants. This includes ethylene glycol and fluorinated coolants. Chemraz® can handle processes at high temperatures of 200°C or more.



Heat exchanger

(All Glands)

SEAL DESIGN SOLUTIONS





O-ring

(All Glands)

GREENE TWEED OVERVIEW

SOLUTIONS BY PROCESS AREA

Click on the

Elastomer Selection

Wheel to

Chemraz®

material

options

Click on the compound for more information.

Chemraz® 551 | Chemraz® 570

explore other

Dielectric Etch

Conductor Etch

Ash/Strip

PECVD/PEALD

Wet Processing

SubFab

ADDITIONAL RESOURCES

Seal Handling Training

Chemical Compatibility Guide

Contact a Greene Tweed sealing solutions engineer to learn how we can help solve your application concerns.

gtweed.com

(All Gland)

next >



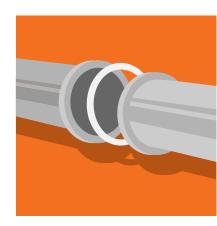
Chemraz® SubFab is a first-to-market total sealing solution that is specifically designed to withstand the highly corrosive environments that are commonly seen in today's SubFab applications.

SUBFAB SOLUTIONS

Complex chemistries in semiconductor processes require robust seals in the SubFab

Greene Tweed's Chemraz® sealing solutions can provide customers the following benefits:

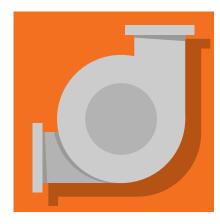
- Increased MTBR (mean time between replacement)
- Improved reliability
- Enhanced repeatability
- Maximum system uptime
- Lower cost of ownership



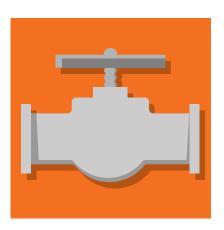
Vacuum Line Solutions



Abatement Solutions



Pump Solutions



Gate Valve Solutions

GREENE TWEED OVERVIEW

SOLUTIONS BY PROCESS AREA

Dielectric Etch

Conductor Etch

Ash/Strip

PECVD/PEALD

Wet Processing

SubFab

ADDITIONAL RESOURCES

Seal Handling Training

Chemical Compatibility Guide



Vacuum Line Solutions

300° _

250° -

200°

150°

100°

50°

GREENE TWEED OVERVIEW

SOLUTIONS BY PROCESS AREA

Dielectric Etch

Conductor Etch

Ash/Strip

PECVD/PEALD

Wet Processing

SubFab

SUBFAR COMPANY A COMPANY A

Click on the

Elastomer

Selection

Wheel to

Chemraz®

material

options

explore other

Click on the compound for more information.

Chemraz® 555 | Fusion® F07

SUBFAB SOLUTIONS



Vacuum Line Solutions



Pump Solutions



Abatement Solutions



Gate Valve Solutions

Product comparison by temperature resistance

SEAL DESIGN SOLUTIONS



Chemraz® 555

Open volume remains

No seal extrusion

• Flanges not pushed apart

to 300°C

Custom seal compressed

O-Ring (All Glands)



KF Custom Seals
(High Temp)



As shown in the graphic below, Chemraz® solutions can be used in vacuum line applications up

to 300°C and are compatible with deposition and etch process exhaust (fluorene and oxygen).

ISO o-ring compressed

Seal starts extruding

Potential damage to seal

Greene Tweed also offers Aluminum 6061-T6 and stainless steel kits in this application.

Fusion® F07

to 180°C

KF Standard and Custom O-ring





ADDITIONAL RESOURCES

Seal Handling Training

Chemical Compatibility Guide

Contact a Greene Tweed sealing solutions engineer to learn how we can help solve your application concerns.



Pump Solutions

SOLUTIONS BY PROCESS AREA

Chemraz® solutions can be used in vacuum pump applications up to 300°C and are compatible with deposition and etch process exhaust gases such as fluorine and oxygen. They are also compatible with fluorinated lubricants commonly used in semiconductor rough pumping applications.

GREENE TWEED OVERVIEW

Conductor Etch

Dielectric Etch

Ash/Strip

PECVD/PEALD

Wet Processing

SubFab





Pump Solutions

Vacuum Line Solutions

SUBFAB SOLUTIONS



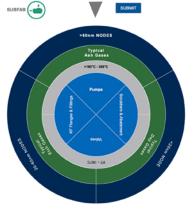
Abatement Solutions



Gate Valve Solutions

FFKM O-rings Only PTFE Barrier and FFKM O-rings

Seals within a EH mechanical booster pump



Click on the compound for more information.

Chemraz® 555 | Fusion® F07

Elastomer Selection Wheel to explore other Chemraz* material options

Click on the

ADDITIONAL RESOURCES

Seal Handling Training

Chemical Compatibility Guide

SEAL DESIGN SOLUTIONS



O-Ring (All Glands)







Shielded Seal (All Glands)



Abatement Solutions

SOLUTIONS BY PROCESS AREA

GREENE TWEED OVERVIEW

Dielectric Etch

Conductor Etch

Ash/Strip

PECVD/PEALD

Wet Processing

ADDITIONAL

RESOURCES

Seal Handling

Compatibility Guide

Training

Chemical

SubFab

Click on the compound for more information.

Click on the

Elastomer

Selection

Wheel to

material

options

explore other Chemraz®

Chemraz® 555 | Fusion® F07

SUBFAB SOLUTIONS









SEAL DESIGN SOLUTIONS

Abatement system components and seal locations



FFKM

FKM

Air Cyclone

Atomizer Spool

Packer Tower

Acid Drain

Tank

O-Ring (All Glands)



KF Custom Seals (High Temp)



Chemraz® solutions can be used in thermal abatement applications up to 300°C and are compatible

with deposition and etch process exhaust gases such as fluorine and oxygen. They also have high

Inlets and

Inlet Head

Combuster

Weir/Quench

Assembly

Bypass Valves

resistance to water vapor and residual acids formed by the abatement process.

KF Standard and Custom O-ring



Custom Kits

(All components in one kit)

Contact a Greene Tweed sealing solutions engineer to learn how we can help solve your application concerns.



SUBFAB SOLUTIONS

Vacuum Line Solutions

Pump Solutions

Abatement

Gate Valve Solutions

Solutions

Gate Valve Solutions

GREENE TWEED OVERVIEW

SOLUTIONS BY PROCESS AREA

Dielectric Etch

Conductor Etch

Ash/Strip

PECVD/PEALD

Wet Processing

SubFab

Selection Wheel to explore other Chemraz® material options

Click on the

Elastomer

Click on the compound for more information.

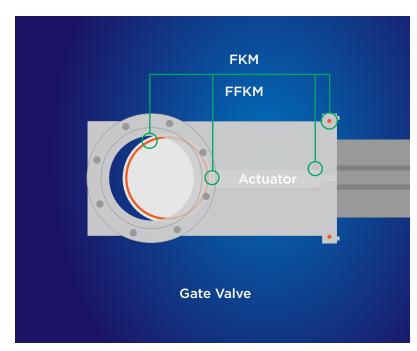
Chemraz® 555 | Fusion® F07

ADDITIONAL RESOURCES

Seal Handling

Chemical Guide

Chemraz® and Fusion® materials are compatible with deposition and etch process exhaust gases such as fluorine and oxygen and deliver cost of ownership and reliability.



Elastomer locations on a gate valve

Training

Compatibility

SEAL DESIGN SOLUTIONS



(Plate/Bonnet)



(Plate)



(Bonnet)



gtweed.com

Greene Tweed

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